# DISCRETE SEMICONDUCTORS



Preliminary specification

2002 May 17





### BGU2003

#### FEATURES

- Low current
- Very high power gain
- Low noise figure
- Integrated temperature compensated biasing
- · Control pin for adjustment bias current
- Supply and RF output pin combined.

### APPLICATIONS

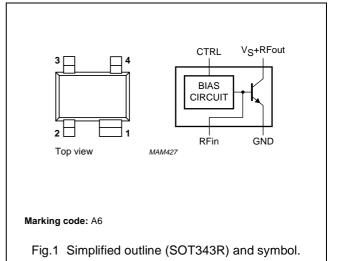
- RF front end
- Wideband applications, e.g. analog and digital cellular telephones, cordless telephones (PHS, DECT, etc.)
- Low noise amplifiers
- Satellite television tuners (SATV)
- High frequency oscillators.

#### DESCRIPTION

Silicon MMIC amplifier consisting of an NPN double polysilicon transistor with integrated biasing for low voltage applications in a plastic, 4-pin SOT343R package.

### PINNING

PIN	DESCRIPTION		
1	GND		
2	RF in		
3	CTRL (bias current control)		
4	V <sub>S</sub> + RF out		



### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Vs	DC supply voltage	RF input AC coupled	-	4.5	V
۱ <sub>S</sub>	DC supply current	V <sub>VS-OUT</sub> = 2.5 V; I <sub>CTRL</sub> = 1 mA; RF input AC coupled	10	_	mA
MSG	maximum stable gain	V <sub>VS-OUT</sub> = 2.5 V; f = 1800 MHz; T <sub>amb</sub> = 25 °C	18	_	dB
NF	noise figure	$V_{VS-OUT}$ = 2.5 V; f = 1800 MHz; $\Gamma_S = \Gamma_{opt}$	1.1	_	dB

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### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Vs	supply voltage	RF input AC coupled	_	4.5	V
V <sub>CTRL</sub>	voltage on control pin		-	2	V
I <sub>S</sub>	supply current (DC)	forced by DC voltage on RF input or I <sub>CTRL</sub>	-	30	mA
I <sub>CTRL</sub>	control current		-	3	mA
P <sub>tot</sub>	total power dissipation	$T_s \le 100 \ ^{\circ}C$	-	135	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	operating junction temperature		-	150	°C

### THERMAL CHARACTERISTICS

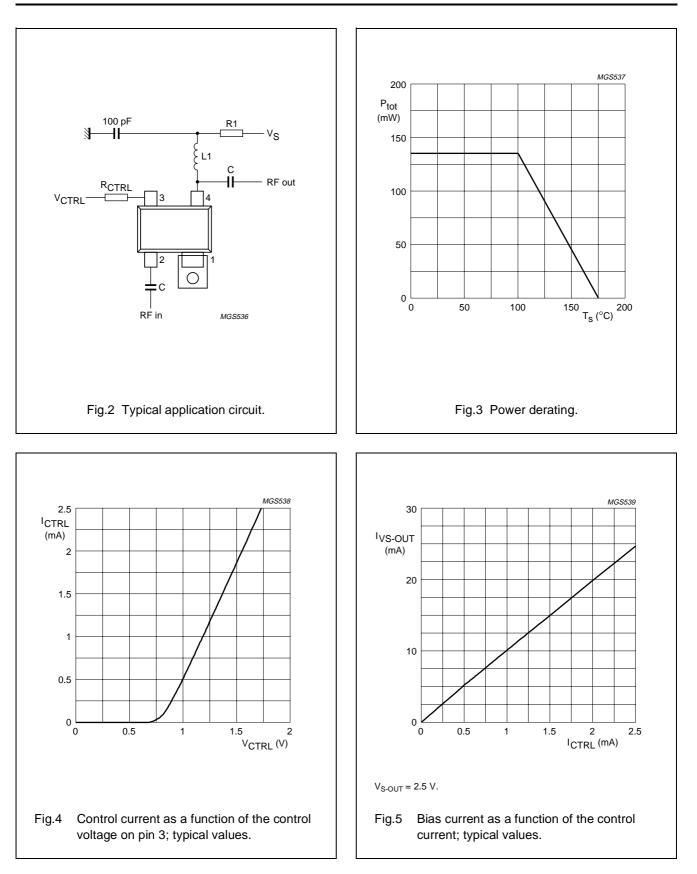
SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	350	K/W

### CHARACTERISTICS

RF input AC coupled;  $T_j = 25 \text{ °C}$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>S</sub>	supply current	$V_{VS-OUT} = 2.5 V; I_{CTRL} = 0.4 mA$	2.5	4.5	6.5	mA
		$V_{VS-OUT} = 2.5 V; I_{CTRL} = 1.0 mA$	6	10	15	mA
MSG	maximum stable gain	V <sub>VS-OUT</sub> = 2.5 V; I <sub>VS-OUT</sub> = 10 mA; f = 900 MHz	-	23	-	dB
		V <sub>VS-OUT</sub> = 2.5 V; I <sub>VS-OUT</sub> = 10 mA; f = 1800 MHz	-	18	-	dB
s <sub>21</sub>   <sup>2</sup>	insertion power gain	V <sub>VS-OUT</sub> = 2.5 V; I <sub>VS-OUT</sub> = 10 mA; f = 900 MHz	18	19	-	dB
		$V_{VS-OUT} = 2.5 V; I_{VS-OUT} = 10 mA;$ f = 1800 MHz	13	14	_	dB
s <sub>12</sub>	isolation	V <sub>VS-OUT</sub> = 2.5 V; I <sub>VS-OUT</sub> = 0; f = 900 MHz	_	26	-	dB
		V <sub>VS-OUT</sub> = 2.5 V; I <sub>VS-OUT</sub> = 0; f = 1800 MHz	-	20	-	dB
NF	noise figure	$V_{VS-OUT} = 2.5 V; I_{VS-OUT} = 10 mA;$ f = 900 MHz; $\Gamma_S = \Gamma_{opt}$	-	1.0	2	dB
		$V_{VS-OUT}$ = 2.5 V; $I_{VS-OUT}$ = 10 mA; f = 1800 MHz; $\Gamma_S = \Gamma_{opt}$	-	1.1	2	dB
IP3 <sub>(out)</sub>	output intercept point; $Z_S = Z_L 50 \Omega$	V <sub>VS-OUT</sub> = 2.3 V; I <sub>VS-OUT</sub> = 10 mA; f = 900 MHz	-	19	_	dBm
		$V_{VS-OUT}$ = 2.3 V; $I_{VS-OUT}$ = 10 mA; f = 1800 MHz	—	21	-	dBm

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	S <sub>11</sub>		s <sub>11</sub> s <sub>21</sub>		s <sub>12</sub>		s <sub>22</sub>		
f (MHz)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	
100	0.837	-10.6	19.216	163.9	0.007	77.3	0.976	-7.1	
200	0.783	-19.9	17.589	151.7	0.012	77.2	0.920	-13.2	
300	0.713	-28.4	16.321	142.4	0.018	76.7	0.861	-17.1	
400	0.645	-36.0	15.046	134.5	0.022	72.9	0.805	-19.8	
500	0.581	-42.0	13.701	127.7	0.027	75.2	0.759	-21.9	
600	0.519	-47.1	12.709	121.6	0.031	74.8	0.718	-22.8	
700	0.474	-50.8	11.602	116.8	0.034	75.0	0.689	-23.4	
800	0.433	-53.3	10.631	112.6	0.038	75.3	0.664	-24.1	
900	0.397	-55.2	9.791	108.8	0.042	76.3	0.644	-24.4	
1000	0.369	-56.9	8.951	106.0	0.046	76.1	0.627	-25.2	
1100	0.342	-58.4	8.314	103.6	0.050	77.3	0.610	-25.6	
1200	0.320	-60.2	7.730	101.1	0.055	77.6	0.599	-26.4	
1300	0.301	-62.1	7.275	99.4	0.058	78.4	0.591	-27.2	
1400	0.286	-64.4	6.912	97.1	0.063	78.1	0.583	-28.0	
1500	0.273	-66.7	6.493	94.8	0.066	78.2	0.578	-28.6	
1600	0.262	-68.5	6.078	93.5	0.071	78.9	0.572	-29.0	
1700	0.252	-7.08	5.783	91.8	0.074	78.9	0.564	-29.6	
1800	0.241	-73.7	5.475	90.9	0.078	79.8	0.553	-30.0	
1900	0.229	-77.0	5.289	89.9	0.083	79.7	0.543	-30.7	
2000	0.221	-81.1	5.094	88.4	0.088	79.5	0.530	-31.9	
2100	0.216	-85.5	4.911	87.2	0.092	79.4	0.518	-33.6	
2200	0.215	-88.9	4.779	85.6	0.098	79.6	0.512	-35.6	
2300	0.229	-91.6	4.588	84.3	0.104	78.7	0.515	-38.2	
2400	0.237	-97.0	4.446	83.8	0.107	78.6	0.515	-40.7	
2500	0.240	-99.3	4.325	82.3	0.111	79.1	0.523	-42.3	
2600	0.243	-101.1	4.145	81.9	0.115	80.1	0.532	-43.0	
2700	0.243	-102.9	4.105	81.6	0.121	80.4	0.537	-43.3	
2800	0.238	-104.9	4.038	80.2	0.124	80.4	0.538	-43.0	
2900	0.233	-106.8	3.924	78.5	0.129	80.3	0.532	-43.2	
3000	0.224	-109.0	3.795	76.7	0.132	80.0	0.519	-43.1	

### Scattering parameters: V<sub>S</sub> = 2.5 V; I<sub>S</sub> = 10 mA; T<sub>amb</sub> = 25 °C

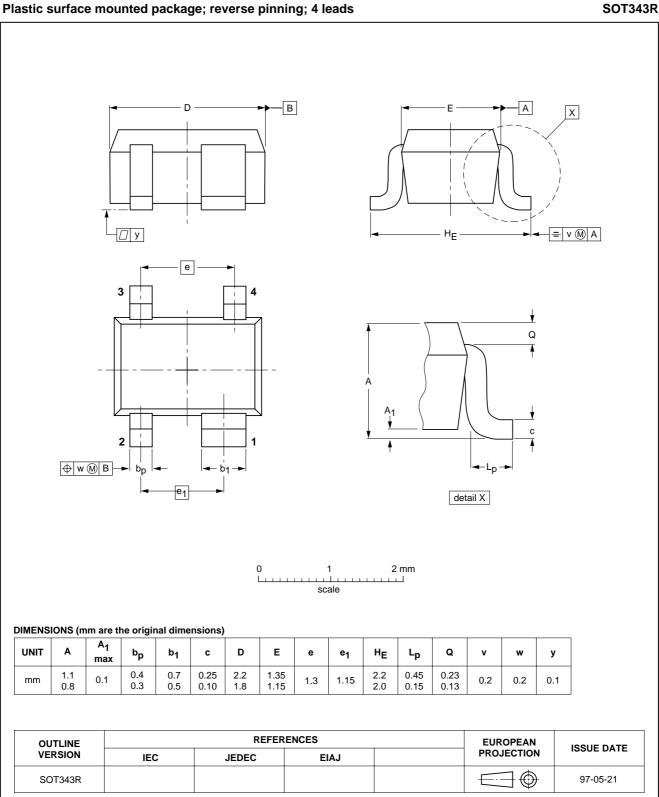
### Noise parameters: V\_S = 2.5 V; I\_S = 10 mA; T\_{amb} = 25 $^\circ\text{C}$

£ (ML)=)		gamma or	ot.	B / 50 O
f (MHz)	NF <sub>min</sub> (dB)	MAGNITUDE (ratio)	ANGLE (deg)	<b>R<sub>n</sub> / 50</b> Ω
900	1.0	0.19	14	0.16
1800	1.1	0.08	60	0.14
2500	1.3	0.07	90	0.14

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# SiGe MMIC amplifier

### PACKAGE OUTLINE



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Printed in The Netherlands

125006/04/pp8

Date of release: 2002 May 17

Document order number: 9397 750 09849

SCA73

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